






General

- High Inrush withstand capability
- Wire-In-Air performance
- Wide range of current rating available
- 6.1mm× 2.5mm square shape surface mount
- Higher temperature profiles
- -55°C~125°C operating temperature
- Excellent environmental integrity
- RoHS compliant
- Halogen-free

Agency / Certificate Information

Agency	File Number	Ampere Range
	E319512	0.5A~5A
	J50260452	0.5A~5A
	SU05049-15003A	0.5A
	SU05049-15001	1A~2.5A
	SU05049-15002	3A~5A

Application

- Battery pack
- Power supply
- PC & PC peripherals
- Wireless basestation
- Industrial equipment
- Telecom system
- LCD monitor and modules
- Medical equipment

Electrical Specifications

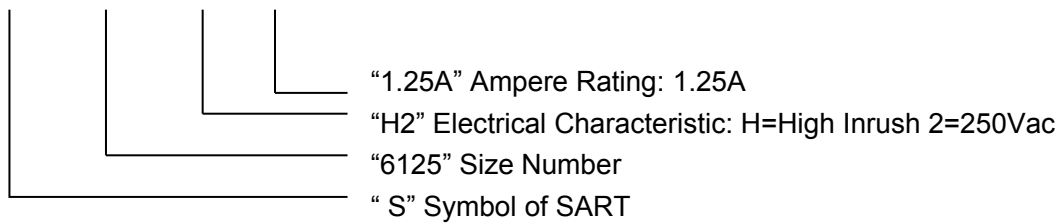
Part Number	Current Rating (A)	Voltage Rating (V)	Interrupting Rating (V)	Typical Cold DCR* (mΩ)	Typical I ² T** (A ² s)
S6125-H2-0.5A	0.5	250	UL/TUV/KC: 35A 250V AC 50A 125V DC	255.00	0.30
S6125-H2-1.0A	1	250		110.00	3.00
S6125-H2-1.25A	1.25	250		82.00	4.10
S6125-H2-1.5A	1.5	250		78.00	4.85
S6125-H2-1.6A	1.6	250		65.00	5.78
S6125-H2-2.0A	2	250		55.00	6.41
S6125-H2-2.5A	2.5	250		38.00	13.75
S6125-H2-3.0A	3	250		27.00	14.51
S6125-H2-3.15A	3.15	250		24.00	17.36
S6125-H2-3.5A	3.5	250		23.00	21.88
S6125-H2-4.0A	4	250		18.00	25.21
S6125-H2-5.0A	5	250		12.00	30.00

* Measured at ≤10% rated current and 25°C

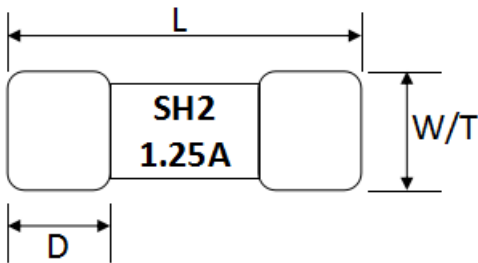
** Melting I²T at 10 times of rated current

Part Number Information

S 6125–H2–1.25A

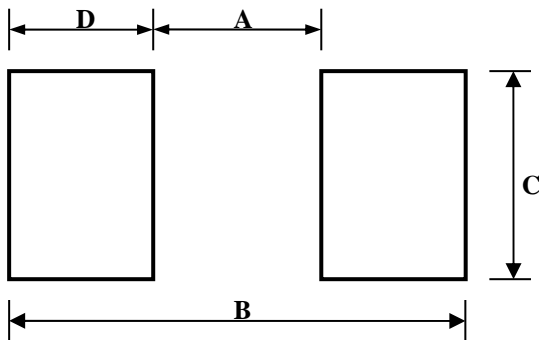


Dimensions



Type	L (mm)	W/ T (mm)	D (mm)
S6125	6.10±0.20	2.50±0.10	1.40±0.10

Recommended Land Patterns



Materials

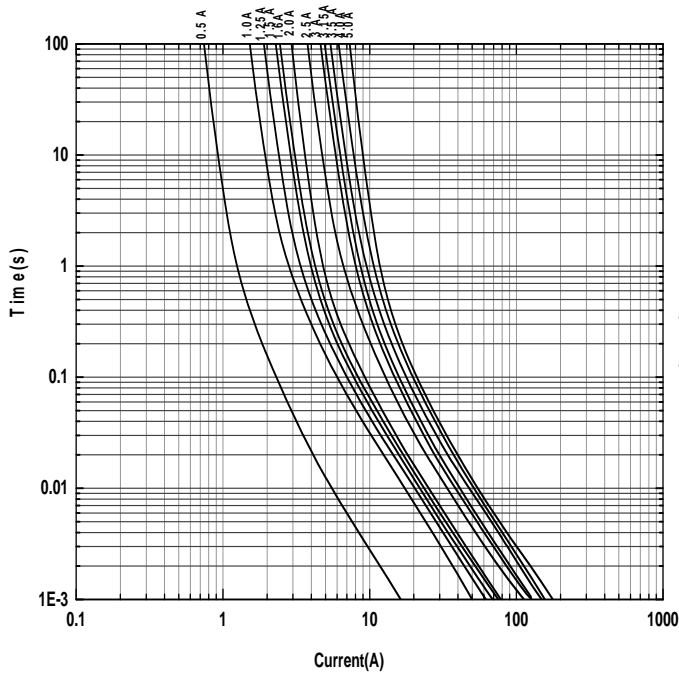
Components	Material
Body	Ceramic
Terminations	Au Plated Brass Cap
Element	Nickel alloy or Copper Alloy

Dimensions	A(mm)	B(mm)	C(mm)	D(mm)
Spec	3.00±0.30	8.00±0.30	3.00±0.30	2.50±0.30

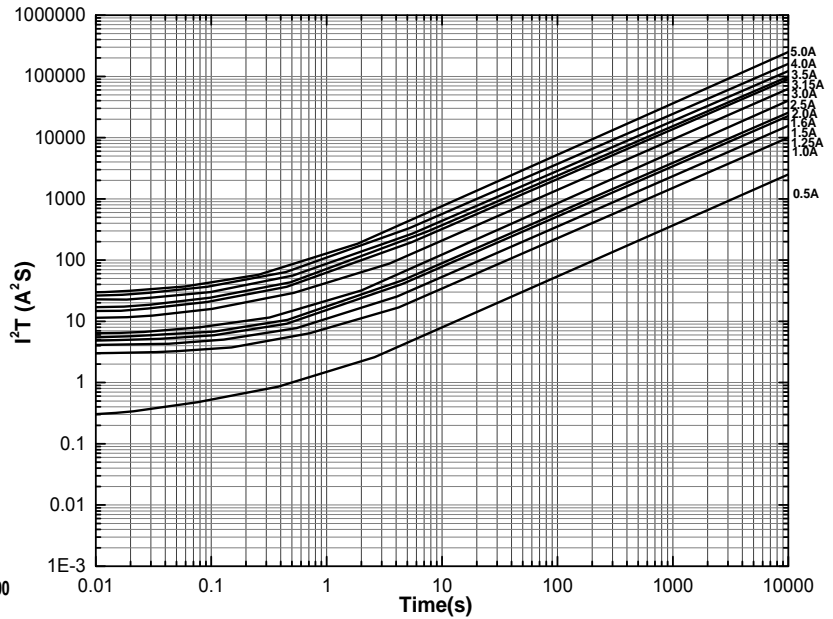
Dimensions of Standard Test Board

Type	Ampere Rating	Board Thickness (mm)	Copper Layer Thickness (mm)	Copper Trace Width (mm)
S6125	0.5A~5A	1.6	0.035	5

Time Current Curve



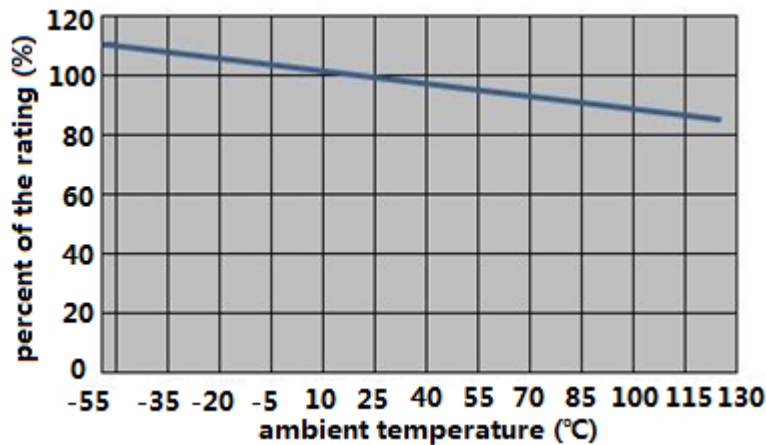
I²T VS Time Curve



Electrical Characteristics

Type	Ampere Rating	% of Current Rating	Opening Time
S6125	0.5A~5A	100	4hours Min.
	0.5A~5A	125	1hour Min.
	0.5A~5A	200	120sec Max.

Temperature Derating Curve



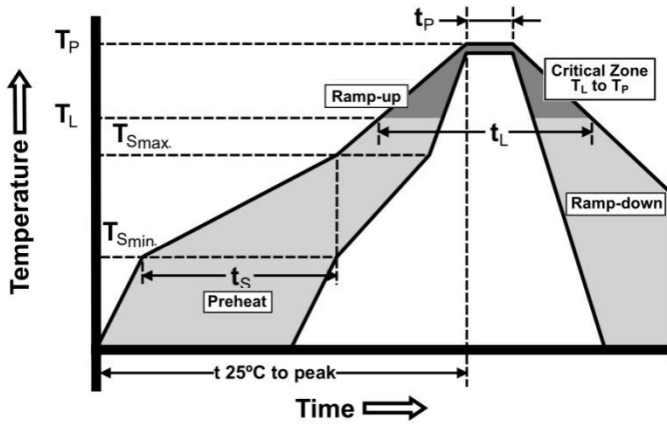
Product Characteristics

Item	Test condition/ Methods	Performance	Standard
Time/Current	100% of current rating	No Fusing, 4hours Min.	UL248-14
	200% of current rating	< 120sec	SART SPEC
	1000% of current rating	10ms~60ms	IEC60127-4
Voltage Drop	100% of current rating	<300mV	IEC-60127-4
Endurance Test	Repeating 100 cycles of 100% of current rating for 1hour "ON", for 15min "OFF", then following by 1hour of 125% of current rating and testing Temperature rise	$ \Delta R $: <10% ΔT : <75°C	IEC-60127-4
Interrupting Ability	0.5A: 35A 250V AC 50A 125V DC 1A~5A: 50A 250VAC 50A 125VDC	without permanent arcing, ignition and bursting of fuse link	UL248-14 IEC60127-4
Solder ability	240°C±5°C, 3sec±0.5sec	95% coverage Min.	IEC60127-4 IEC60068-2-20; MIL-STD-202
Resistance to Soldering	260°C±5°C, 10sec±0.5sec	$ \Delta R $:<10%	MIL-STD-202 Method 210
High Temperature Operating Life	T=70°C±2°C, 60% of current rating, 96 hours	$ \Delta R $: <10%	MIL-STD-202 Method 108
Humidity (Steady State)	T=40°C±2°C, RH=90%~95%, 1000 hours	$ \Delta R $: <10%	MIL-STD-202 Method 103
Low Temperature Storage	T=-55°C±3°C, 96 hours	$ \Delta R $: <10%	IEC60068-2-1
High Temperature Storage	T=125°C±2°C, 96 hours	$ \Delta R $: <10%	IEC60068-2-2
Salt Spray	5% salt solution, 48 hours	$ \Delta R $: <10%	MIL-STD-202 Method 101
Thermal Shock	100 cycles, -65°C to +125°C, 30 minutes@each extreme	$ \Delta R $: <(10%R+0.005Ω)	IEC 60068-2-14

Recommended Solder Curve

1. Infrared Reflow:

- Temperature: 260°C
- Time: 5sec Max.
- Recommend Reflow profile



Profile Feature	Pb-Free Assembly
Average Ramp-up Rate(T_{Smax} to T_p)	3°C/sec Max.
Preheat Temperature Min. (T_{Smin})	150°C
Preheat Temperature Max. (T_{Smax})	200°C
Preheat Time (T_{Smin} to T_{Smax})	60sec~120sec
Peak Temperature (T_p)	260°C
Time within 5°C of actual Peak Temperature (T_p)	5sec
Melting tin time (T_L)	20sec~40sec
Ramp-down Rate	6°C/sec Max.
Time 25°C to peak Temperature	8minutes Max.

2. Wave soldering

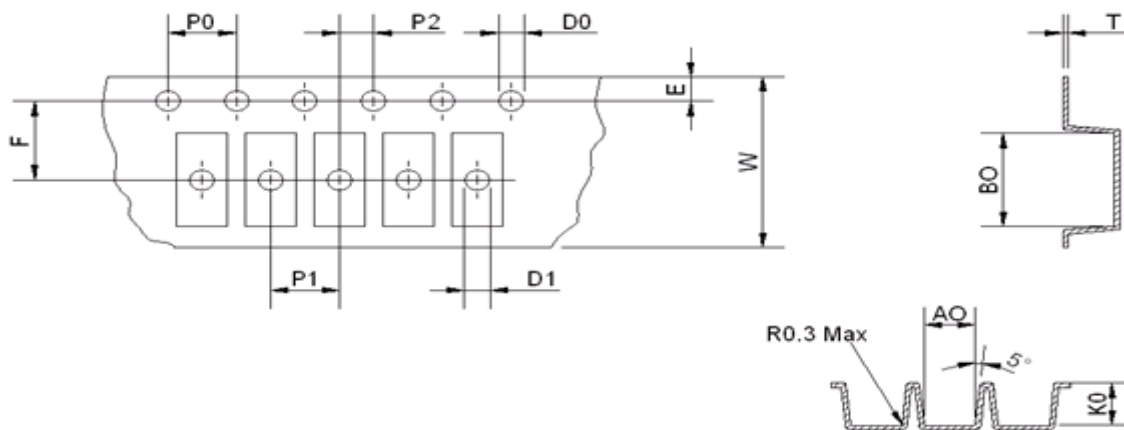
- Reservoir Temperature: 260°C
- Time in Reservoir: 10secMax.

3. Hand Soldering

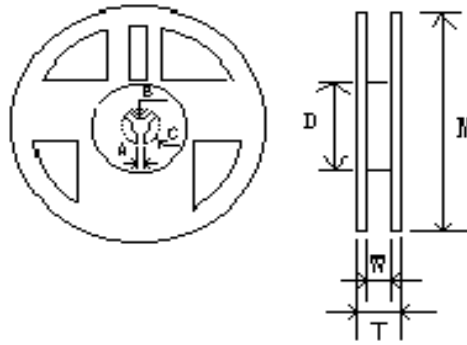
- Temperature: 300°C
- Time: 2secMax.
- Soldering iron avoid touch Brass Cap.

Packaging

- 1000 pieces of fuses in emboss taper and reeled on a 178mm(7 inch) reel.



Type	A0(mm)	B0(mm)	K0(mm)	P0(mm)	P1(mm)	P2(mm)
Spec	2.70±0.10	6.40±0.10	2.70±0.10	4.00±0.10	4.00±0.10	2.00±0.10
Type	E(mm)	F(mm)	D0(mm)	D1(mm)	W(mm)	T(mm)
Spec	1.75±0.10	5.50±0.10	1.50±0.10	1.50±0.25	12.00±0.15	0.25±0.05



Type	M(mm)	W(mm)	T(mm)	A(mm)	B(mm)	C(mm)	D(mm)
Spec	178.00±2.00	12.50±1.00	14.50±1.50	2.00±0.50	13.00±0.50	21.00±0.50	58.00±2.00

Storage

- The ambient temperature recommended for storage shall be between 5°C~30°C.
- The relative humidity recommended for storage shall be between 25%RH~60%RH.
- Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.